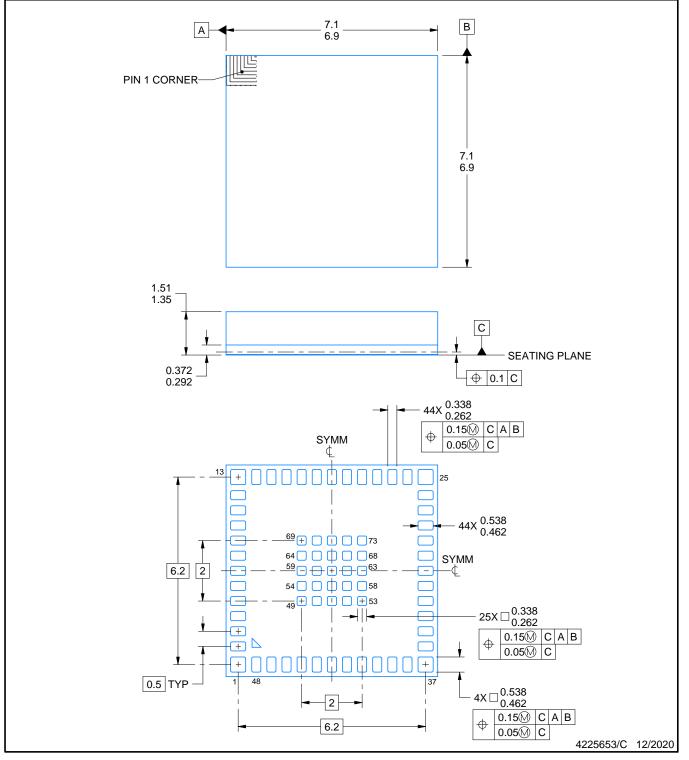
PACKAGE OUTLINE

QFM - 1.51 mm max height

QUAD FLAT MODULE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice.



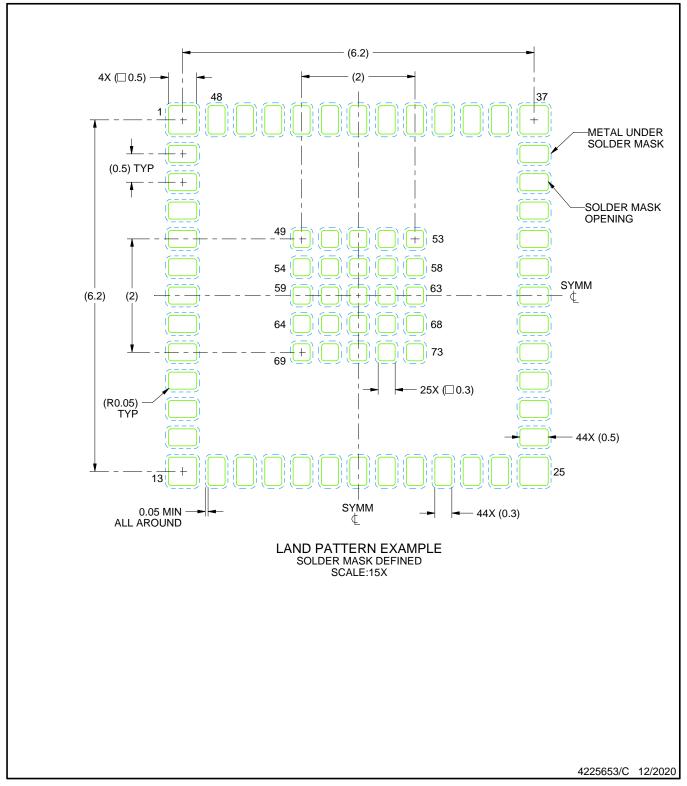
MOT0048A

MOT0048A

EXAMPLE BOARD LAYOUT

QFM - 1.51 mm max height

QUAD FLAT MODULE



NOTES: (continued)

3. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

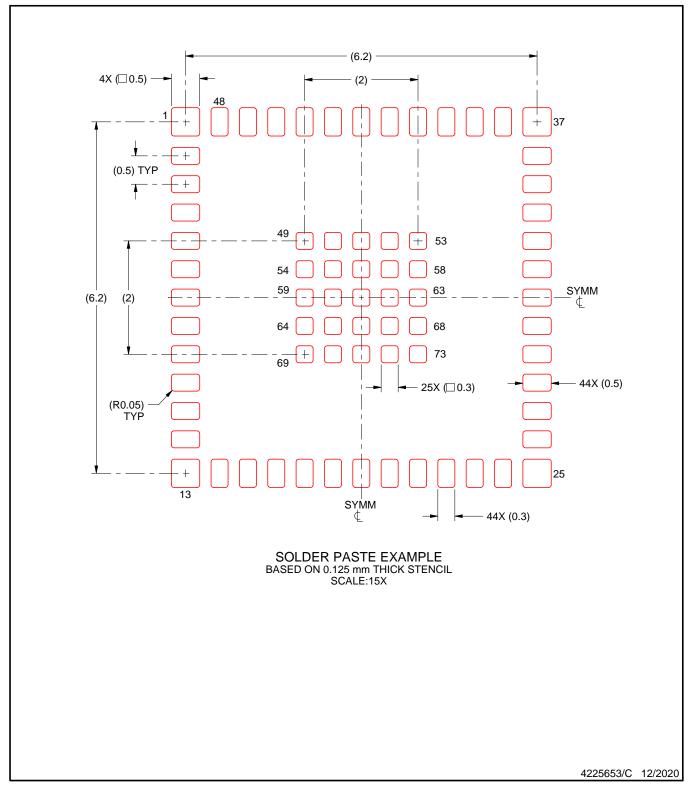


MOT0048A

EXAMPLE STENCIL DESIGN

QFM - 1.51 mm max height

QUAD FLAT MODULE



NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.



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